### INTEGRATED CIRCUITS



Product specification Supersedes data of 1996 Dec 03 File under Integrated Circuits, IC12 1997 Apr 02



### CONTENTS

1	FEATURES
2	GENERAL DESCRIPTION
3	ORDERING INFORMATION
4	BLOCK DIAGRAM
5	PINNING
6	FUNCTIONAL DESCRIPTION
6.1	Power-on reset
6.2	LCD bias generator
6.3	LCD voltage selector
6.4	LCD drive mode waveforms
6.5	Oscillator
6.6	Internal clock
6.7	External clock
6.8	Timing
6.9	Display latch
6.10	Shift register
6.11	Segment outputs
6.12	Backplane outputs
6.13	Display RAM
6.14	Data pointer
6.15	Subaddress counter
6.16	Output bank selector
6.17	Input bank selector
6.18	Blinker
7	I <sup>2</sup> C-BUS DESCRIPTION
7.1	Bit transfer
7.2	Start and stop conditions
7.3	System configuration
7.4	Acknowledge
7.5	PCF8566 I <sup>2</sup> C-bus controller
7.6	Input filters
7.7	I <sup>2</sup> C-bus protocol
7.8	Command decoder
7.9	Display controller
7 10	Cascaded operation

7.10 Cascaded operation

Product specification
-----------------------

8	LIMITING VALUES
9	HANDLING
10	DC CHARACTERISTICS
11	AC CHARACTERISTICS
12	APPLICATION INFORMATION
13	CHIP DIMENSIONS AND BONDING PAD LOCATIONS
14	PACKAGE OUTLINES
15	SOLDERING
15.1	Introduction
15.2	DIP
15.2.1	Soldering by dipping or by wave
15.2.2	Repairing soldered joints
15.3	SO and VSO
15.3.1	Reflow soldering
15.3.2	Wave soldering
15.3.3	Repairing soldered joints
16	DEFINITIONS
17	LIFE SUPPORT APPLICATIONS
18	PURCHASE OF PHILIPS I <sup>2</sup> C COMPONENTS



#### 1 FEATURES

- Single-chip LCD controller/driver
- Selectable backplane drive configuration: static or 2, 3 or 4 backplane multiplexing
- Selectable display bias configuration: static,  $^{1}\!\!\!/_{2}$  or  $^{1}\!\!/_{3}$
- Internal LCD bias generation with voltage-follower buffers
- 24 segment drives: up to twelve 8-segment numeric characters; up to six 15-segment alphanumeric characters; or any graphics of up to 96 elements
- $24 \times 4$ -bit RAM for display data storage
- Auto-incremented display data loading across device subaddress boundaries
- Display memory bank switching in static and duplex drive modes
- Versatile blinking modes
- · LCD and logic supplies may be separated
- 2.5 to 6 V power supply range
- Low power consumption
- Power saving mode for extremely low power consumption in battery-operated and telephone applications
- I<sup>2</sup>C-bus interface
- TTL/CMOS compatible
- Compatible with any 4-bit, 8-bit or 16-bit microprocessors/microcontrollers
- May be cascaded for large LCD applications (up to 1536 segments possible)
- Cascadable with the 40 segment LCD driver PCF8576C
- Optimized pinning for single plane wiring in both single and multiple PCF8566 applications
- Space-saving 40 lead plastic very small outline package (VSO40; SOT158-1)
- No external components required (even in multiple device applications)
- Manufactured in silicon gate CMOS process.

#### **3 ORDERING INFORMATION**

#### 2 GENERAL DESCRIPTION

The PCF8566 is a peripheral device which interfaces to almost any Liquid Crystal Display (LCD) having low multiplex rates. It generates the drive signals for any static or multiplexed LCD containing up to four backplanes and up to 24 segments and can easily be cascaded for larger LCD applications. The PCF8566 is compatible with most microprocessors/microcontrollers and communicates via a two-line bidirectional I<sup>2</sup>C-bus. Communication overheads are minimized by a display RAgmM with auto-incremented addressing, by hardware subaddressing and by display memory switching (static and duplex drive modes).

TYPE NUMBER	PACKAGE				
ITFE NUMBER	NAME	DESCRIPTION	VERSION		
PCF8566P	DIP40	plastic dual in-line package; 40 leads (600 mil)	SOT129-1		
PCF8566T	VSO40	plastic very small outline package; 40 leads	SOT158-1		

#### 4 BLOCK DIAGRAM



PCF8566

Product specification

#### 5 PINNING

SYMBOL	PIN	DESCRIPTION
SDA	1	I <sup>2</sup> C-bus data input/output
SCL	2	I <sup>2</sup> C-bus clock input/output
SYNC	3	cascade synchronization input/output
CLK	4	external clock input/output
V <sub>DD</sub>	5	positive supply voltage
OSC	6	oscillator input
A0	7	
A1	8	I <sup>2</sup> C-bus subaddress inputs
A2	9	
SA0	10	I <sup>2</sup> C-bus slave address bit 0 input
V <sub>SS</sub>	11	logic ground
V <sub>LCD</sub>	12	LCD supply voltage
BP0	13	
BP2	14	LCD backplane outputs
BP1	15	LCD backplane outputs
BP3	16	
S0 to S23	17 to 40	LCD segment outputs



#### 6 FUNCTIONAL DESCRIPTION

The PCF8566 is a versatile peripheral device designed to interface any microprocessor to a wide variety of LCDs. It can directly drive any static or multiplexed LCD containing up to 4 backplanes and up to 24 segments. The display configurations possible with the PCF8566 depend on the number of active backplane outputs required; a selection of display configurations is given in Table 1. All of the display configurations given in Table 1 can be implemented in the typical system shown in Fig.3. The host microprocessor/microcontroller maintains the two-line l<sup>2</sup>C-bus communication channel with the PCF8566. The internal oscillator is selected by tying OSC (pin 6) to V<sub>SS</sub>. The appropriate biasing voltages for the multiplexed LCD waveforms are generated internally. The only other connections required to complete the system are to the power supplies (V<sub>DD</sub>, V<sub>SS</sub> and V<sub>LCD</sub>) and to the LCD panel chosen for the application.

ACTIVE BACKPLANE OUTPUTS	NUMBER OF SEGMENTS	7-SEGMENT NUMERIC	14-SEGMENT ALPHANUMERIC	DOT MATRIX
4	96	12 digits + 12 indicator symbols	6 characters + 12 indicator symbols	96 dots (4 × 24)
3	72	9 digits + 9 indicator symbols	4 characters + 16 indicator symbols	72 dots (3 × 24)
2	48	6 digits + 6 indicator symbols	3 characters + 6 indicator symbols	48 dots (2 × 24)
1	24	3 digits + 3 indicator symbols	1 character + 10 indicator symbols	24 dots

 Table 1
 Selection of display configurations



#### 6.1 Power-on reset

At power-on the PCF8566 resets to a defined starting condition as follows:

- 1. All backplane outputs are set to  $V_{\text{DD}}$
- 2. All segment outputs are set to V<sub>DD</sub>
- 3. The drive mode '1 : 4 multiplex with  $\frac{1}{3}$  bias' is selected
- 4. Blinking is switched off
- 5. Input and output bank selectors are reset (as defined in Table 5)
- 6. The I<sup>2</sup>C-bus interface is initialized
- 7. The data pointer and the subaddress counter are cleared.

Data transfers on the  $l^2$ C-bus should be avoided for 1 ms following power-on to allow completion of the reset action.

#### 6.2 LCD bias generator

The full-scale LCD voltage (V<sub>op</sub>) is obtained from  $V_{DD} - V_{LCD}$ . The LCD voltage may be temperature compensated externally through the V<sub>LCD</sub> supply to pin 12. Fractional LCD biasing voltages are obtained from an internal voltage divider of three series resistors connected between V<sub>DD</sub> and V<sub>LCD</sub>. The centre resistor can be switched out of circuit to provide a  $\frac{1}{2}$ bias voltage level for the 1 : 2 multiplex configuration.

#### 6.3 LCD voltage selector

The LCD voltage selector coordinates the multiplexing of the LCD according to the selected LCD drive configuration. The operation of the voltage selector is controlled by MODE SET commands from the command decoder. The biasing configurations that apply to the preferred modes of operation, together with the biasing characteristics as functions of  $V_{op} = V_{DD} - V_{LCD}$  and the resulting discrimination ratios (D), are given in Table 2.

A practical value of  $V_{op}$  is determined by equating  $V_{off(rms)}$  with a defined LCD threshold voltage (V<sub>th</sub>), typically when the LCD exhibits approximately 10% contrast. In the static drive mode a suitable choice is  $V_{op} \geq 3 \ V_{th}$ . Multiplex drive ratios of 1 : 3 and 1 : 4 with  $1_2$  bias are possible but the discrimination and hence the contrast ratios are smaller

 $(\sqrt{3} = 1.732 \text{ for } 1:3 \text{ multiplex or } \sqrt{21}/3 = 1.528 \text{ for } 1:4 \text{ multiplex})$ . The advantage of these modes is a reduction of the LCD full scale voltage V<sub>op</sub> as follows:

1 : 3 multiplex (
$$\frac{1}{2}$$
bias):  
 $V_{op} = \sqrt{6}V_{op(mrs)} = 2.449V_{off(rms)}$   
1 : 4 multiplex ( $\frac{1}{2}$ bias):

 $V_{op} = \sqrt[4]{3/3}V_{off(rms)} = 2.309V_{off(rms)}$ 

These compare with  $V_{op} = 3 V_{off(rms)}$  when  $\frac{1}{3}$  bias is used.

#### Table 2 Preferred LCD drive modes: summary of characteristics

LCD DRIVE MODE	LCD BIAS CONFIGURATION	$\frac{V_{off(rms)}}{V_{op}}$	$\frac{V_{on (rms)}}{V_{op}}$	$D = \frac{V_{on  (rms)}}{V_{off  (rms)}}$
Static (1 BP)	static (2 levels)	0	1	×
1 : 2 MUX (2 BP)	<sup>1</sup> ⁄ <sub>2</sub> (3 levels)	$\sqrt{2}/4 = 0.354$	$\sqrt{10}/4 = 0.791$	$\sqrt{5} = 2.236$
1 : 2 MUX (2 BP)	$\frac{1}{3}$ (4 levels)	$\frac{1}{3} = 0.333$	$\sqrt{5}/3 = 0.745$	$\sqrt{5} = 2.236$
1 : 3 MUX (3 BP)	$\frac{1}{3}$ (4 levels)	$\frac{1}{3} = 0.333$	$\sqrt{33}/9 = 0.638$	$\sqrt{33}/3 = 1.915$
1 : 4 MUX (4 BP)	$\frac{1}{3}$ (4 levels)	<sup>1</sup> / <sub>3</sub> = 0.333	$\sqrt{3}/3 = 0.577$	$\sqrt{3} = 1.732$

#### 6.4 LCD drive mode waveforms

The static LCD drive mode is used when a single backplane is provided in the LCD. Backplane and segment drive waveforms for this mode are shown in Fig.4.

When two backplanes are provided in the LCD the 1 : 2 multiplex drive mode applies. The PCF8566 allows use of  $\frac{1}{2}$  or  $\frac{1}{3}$  bias in this mode as shown in Figs 5 and 6.

The backplane and segment drive waveforms for the 1 : 3 multiplex drive mode (three LCD backplanes) and for the 1 : 4 multiplex drive mode (four LCD backplanes) are shown in Figs 7 and 8 respectively.











#### 6.5 Oscillator

The internal logic and the LCD drive signals of the PCF8566 or PCF8576 are timed either by the built-in oscillator or from an external clock.

The clock frequency ( $f_{CLK}$ ) determines the LCD frame frequency and the maximum rate for data reception from the I<sup>2</sup>C-bus. To allow I<sup>2</sup>C-bus transmissions at their maximum data rate of 100 kHz,  $f_{CLK}$  should be chosen to be above 125 kHz.

A clock signal must always be supplied to the device; removing the clock may freeze the LCD in a DC state.

#### 6.6 Internal clock

When the internal oscillator is used, OSC (pin 6) should be tied to  $V_{SS}$ . In this case, the output from CLK (pin 4) provides the clock signal for cascaded PCF8566s and PCF8576s in the system.

#### 6.7 External clock

The condition for external clock is made by tying OSC (pin 6) to  $V_{DD}$ ; CLK (pin 4) then becomes the external clock input.

#### 6.8 Timing

The timing of the PCF8566 organizes the internal data flow of the device. This includes the transfer of display data from the display RAM to the display segment outputs. In cascaded applications, the synchronization signal SYNC maintains the correct timing relationship between the PCF8566s in the system. The timing also generates the LCD frame frequency which it derives as an integer multiple of the clock frequency (Table 3). The frame frequency is set by MODE SET commands when internal clock is used, or by the frequency applied to pin 4 when external clock is used.

Table 3	LCD frame	e frequencies
Table J	LOD maine	

PCF8566 MODE	f <sub>frame</sub>	NOMINAL f <sub>frame</sub> (Hz)
Normal mode	f <sub>CLK</sub> /2880	64
Power saving mode	f <sub>CLK</sub> /480	64

The ratio between the clock frequency and the LCD frame frequency depends on the mode in which the device is operating. In the power saving mode the reduction ratio is six times smaller; this allows the clock frequency to be reduced by a factor of six. The reduced clock frequency results in a significant reduction in power dissipation. The lower clock frequency has the disadvantage of increasing the response time when large amounts of display data are transmitted on the I<sup>2</sup>C-bus. When a device is unable to 'digest' a display data byte before the next one arrives, it holds the SCL line LOW until the first display data byte is stored. This slows down the transmission rate of the I<sup>2</sup>C-bus but no data loss occurs.

#### 6.9 Display latch

The display latch holds the display data while the corresponding multiplex signals are generated. There is a one-to-one relationship between the data in the display latch, the LCD segment outputs and one column of the display RAM.

#### 6.10 Shift register

The shift register serves to transfer display information from the display RAM to the display latch while previous data are displayed.

#### 6.11 Segment outputs

The LCD drive section includes 24 segment outputs S0 to S23 (pins 17 to 40) which should be connected directly to the LCD. The segment output signals are generated in accordance with the multiplexed backplane signals and with the data resident in the display latch. When less than 24 segment outputs are required the unused segment outputs should be left open-circuit.

#### 6.12 Backplane outputs

The LCD drive section includes four backplane outputs BP0 to BP3 which should be connected directly to the LCD. The backplane output signals are generated in accordance with the selected LCD drive mode. If less than four backplane outputs are required the unused outputs can be left open. In the 1 : 3 multiplex drive mode BP3 carries the same signal as BP1, therefore these two adjacent outputs can be tied together to give enhanced drive capabilities. In the 1 : 2 multiplex drive mode BP0 and BP2, BP1 and BP3 respectively carry the same signals and may also be paired to increase the drive capabilities. In the static drive mode the same signal is carried by all four backplane outputs and they can be connected in parallel for very high drive requirements.

#### 6.13 Display RAM

The display RAM is a static  $24 \times 4$ -bit RAM which stores LCD data. A logic 1 in the RAM bit-map indicates the 'on' state of the corresponding LCD segment; similarly, a logic 0 indicates the 'off' state.

There is a one-to-one correspondence between the RAM addresses and the segment outputs, and between the individual bits of a RAM word and the backplane outputs. The first RAM column corresponds to the 24 segments operated with respect to backplane BP0 (see Fig.9). In multiplexed LCD applications the segment data of the second, third and fourth column of the display RAM are time-multiplexed with BP1, BP2 and BP3 respectively.

When display data are transmitted to the PCF8566 the display bytes received are stored in the display RAM according to the selected LCD drive mode. To illustrate the filling order, an example of a 7-segment numeric display showing all drive modes is given in Fig.10; the RAM filling organization depicted applies equally to other LCD types.

With reference to Fig.10, in the static drive mode the eight transmitted data bits are placed in bit 0 of eight successive display RAM addresses. In the 1 : 2 multiplex drive mode the eight transmitted data bits are placed in bits 0 and 1 of four successive display RAM addresses. In the 1 : 3 multiplex drive mode these bits are placed in bits 0, 1 and 2 of three successive addresses, with bit 2 of the third address left unchanged. This last bit may, if necessary, be controlled by an additional transfer to this address but care should be taken to avoid overriding adjacent data because full bytes are always transmitted. In the 1 : 4 multiplex drive mode the eight transmitted data bits are placed in bits 0, 1, 2 and 3 of two successive display RAM addresses.

#### 6.14 Data pointer

The addressing mechanism for the display RAM is realized using the data pointer. This allows the loading of an individual display data byte, or a series of display data bytes, into any location of the display RAM. The sequence commences with the initialization of the data pointer by the LOAD DATA POINTER command. Following this, an arriving data byte is stored starting at the display RAM address indicated by the data pointer thereby observing the filling order shown in Fig.10. The data pointer is automatically incremented according to the LCD configuration chosen. That is, after each byte is stored, the contents of the data pointer are incremented by eight (static drive mode), by four (1 : 2 multiplex drive mode), by three (1 : 3 multiplex drive mode) or by two (1 : 4 multiplex drive mode).

#### 6.15 Subaddress counter

The storage of display data is conditioned by the contents of the subaddress counter. Storage is allowed to take place only when the contents of the subaddress counter agree with the hardware subaddress applied to A0, A1 and A2 (pins 7, 8, and 9). A0, A1 and A2 should be tied to  $V_{SS}$  or  $V_{DD}$ . The subaddress counter value is defined by the DEVICE SELECT command. If the contents of the subaddress counter and the hardware subaddress do not agree then data storage is inhibited but the data pointer is incremented as if data storage had taken place. The subaddress counter is also incremented when the data pointer overflows.

The storage arrangements described lead to extremely efficient data loading in cascaded applications. When a series of display bytes are being sent to the display RAM, automatic wrap-over to the next PCF8566 occurs when the last RAM address is exceeded. Subaddressing across device boundaries is successful even if the change to the next device in the cascade occurs within a transmitted character.



1997 Apr 02

LCD segments

а

q

d  $\langle \rangle$ 

а

S<sub>n</sub>+2<sup>-</sup>

S<sub>n</sub> + 3

S<sub>n</sub> + 4

S\_ + 5

S\_ + 6

S<sub>n</sub> + 1

S<sub>n</sub> + 2

S\_ + 3

S<sub>n</sub> + 1

S<sub>n</sub> + 2

s<sub>n</sub>.

S<sub>n</sub> + 1

unchanged).

а

d

 $\langle \rangle$ 

s<sub>n</sub>.

drive mode

static

1:2

1:3

1:4

multiplex

multiplex

multiplex

LCD backplanes

BP1

BP2

BP2

BP3

BP0

BP0

BP0

BP1

BP0

BP1

S<sub>n</sub> + 1

S<sub>n</sub> + 7

Óр

) dd

Sn

∩ dp

🔿 dp

Sn

<u>д</u>



display RAM filling order

Philips Semiconductors

rates

transmitted display byte

Universal LCD driver for low multiplex

Product specification

#### 6.16 Output bank selector

This selects one of the four bits per display RAM address for transfer to the display latch. The actual bit chosen depends on the particular LCD drive mode in operation and on the instant in the multiplex sequence. In 1 : 4 multiplex, all RAM addresses of bit 0 are the first to be selected, these are followed by the contents of bit 1, bit 2 and then bit 3. Similarly in 1 : 3 multiplex, bits 0, 1 and 2 are selected sequentially. In 1 : 2 multiplex, bits 0 then 1 are selected and, in the static mode, bit 0 is selected.

The PCF8566 includes a RAM bank switching feature in the static and 1 : 2 multiplex drive modes. In the static drive mode, the BANK SELECT command may request the contents of bit 2 to be selected for display instead of bit 0 contents. In the 1 : 2 drive mode, the contents of bits 2 and 3 may be selected instead of bits 0 and 1. This gives the provision for preparing display information in an alternative bank and to be able to switch to it once it is assembled.

#### 6.17 Input bank selector

The input bank selector loads display data into the display RAM according to the selected LCD drive configuration. Display data can be loaded in bit 2 in static drive mode or in bits 2 and 3 in 1 : 2 drive mode by using the BANK SELECT command. The input bank selector functions independently of the output bank selector.

#### 6.18 Blinker

The display blinking capabilities of the PCF8566 are very versatile. The whole display can be blinked at frequencies selected by the BLINK command. The blinking frequencies are integer multiples of the clock frequency; the ratios between the clock and blinking frequencies depend on the mode in which the device is operating, as shown in Table 4.

An additional feature is for an arbitrary selection of LCD segments to be blinked. This applies to the static and 1 : 2 LCD drive modes and can be implemented without any communication overheads. By means of the output bank selector, the displayed RAM banks are exchanged with alternate RAM banks at the blinking frequency. This mode can also be specified by the BLINK command.

In the 1 : 3 and 1 : 4 multiplex modes, where no alternate RAM bank is available, groups of LCD segments can be blinked by selectively changing the display RAM data at fixed time intervals.

If the entire display is to be blinked at a frequency other than the nominal blinking frequency, this can be effectively performed by resetting and setting the display enable bit E at the required rate using the MODE SET command.

BLINKING MODE	NORMAL OPERATING MODE RATIO	POWER-SAVING MODE RATIO	NOMINAL BLINKING FREQUENCY f <sub>blink</sub> (Hz)
Off	-	-	blinking off
2 Hz	f <sub>CLK</sub> /92160	f <sub>CLK</sub> /15360	2
1 Hz	f <sub>CLK</sub> /184320	f <sub>CLK</sub> /30720	1
0.5 Hz	f <sub>CLK</sub> /368640	f <sub>CLK</sub> /61440	0.5

#### Table 4 Blinking frequencies

#### 7 I<sup>2</sup>C-BUS DESCRIPTION

The I<sup>2</sup>C-bus is for 2-way, 2-line communication between different ICs or modules. The two lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

#### 7.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as control signals.

#### 7.2 Start and stop conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line while the clock is HIGH is defined as the START condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition (P).

#### 7.3 System configuration

A device generating a message is a 'transmitter', a device receiving a message is a 'receiver'. The device that controls the message is the 'master' and the devices which are controlled by the master are the 'slaves'.

#### 7.4 Acknowledge

The number of data bytes transferred between the START and STOP conditions from transmitter to receiver is not limited. Each byte is followed by one acknowledge bit. The acknowledge bit is a HIGH level put on the bus by the transmitter whereas the master generates an extra acknowledge related clock pulse. A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse, set up and hold times must be taken into account. A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event the transmitter must leave the data line HIGH to enable the master to generate a STOP condition.









#### 7.5 PCF8566 I<sup>2</sup>C-bus controller

The PCF8566 acts as an I<sup>2</sup>C-bus slave receiver. It does not initiate I<sup>2</sup>C-bus transfers or transmit data to an I<sup>2</sup>C-bus master receiver. The only data output from the PCF8566 are the acknowledge signals of the selected devices. Device selection depends on the I<sup>2</sup>C-bus slave address, on the transferred command data and on the hardware subaddress.

In single device applications, the hardware subaddress inputs A0, A1 and A2 are normally left open-circuit or tied to  $V_{SS}$  which defines the hardware subaddress 0. In multiple device applications A0, A1 and A2 are left open-circuit or tied to  $V_{SS}$  or  $V_{DD}$  according to a binary coding scheme such that no two devices with a common I<sup>2</sup>C-bus slave address have the same hardware subaddress.

In the power-saving mode it is possible that the PCF8566 is not able to keep up with the highest transmission rates when large amounts of display data are transmitted. If this situation occurs, the PCF8566 forces the SCL line LOW until its internal operations are completed. This is known as the 'clock synchronization feature' of the I<sup>2</sup>C-bus and serves to slow down fast transmitters. Data loss does not occur.

#### 7.6 Input filters

To enhance noise immunity in electrically adverse environments, RC low-pass filters are provided on the SDA and SCL lines.

#### 7.7 I<sup>2</sup>C-bus protocol

Two I<sup>2</sup>C-bus slave addresses (0111110 and 0111111) are reserved for PCF8566. The least-significant bit of the slave address that a PCF8566 will respond to is defined by the level tied at its input SA0 (pin 10). Therefore, two types of PCF8566 can be distinguished on the same I<sup>2</sup>C-bus which allows:

- 1. Up to 16 PCF8566s on the same I<sup>2</sup>C-bus for very large LCD applications
- The use of two types of LCD multiplex on the same I<sup>2</sup>C-bus.

The I<sup>2</sup>C-bus protocol is shown in Fig.15. The sequence is initiated with a START condition (S) from the I<sup>2</sup>C-bus master which is followed by one of the two PCF8566 slave addresses available. All PCF8566s with the corresponding SA0 level acknowledge in parallel the slave address but all PCF8566s with the alternative SA0 level ignore the whole I<sup>2</sup>C-bus transfer. After acknowledgement, one or more command bytes (m) follow which define the status of the addressed PCF8566s. The last command byte is tagged with a cleared most-significant bit, the continuation bit C. The command bytes are also acknowledged by all addressed PCF8566s on the bus.

After the last command byte, a series of display data bytes (n) may follow. These display data bytes are stored in the display RAM at the address specified by the data pointer and the subaddress counter. Both data pointer and subaddress counter are automatically updated and the data are directed to the intended PCF8566 device. The acknowledgement after each byte is made only by the (A0, A1, A2) addressed PCF8566. After the last display byte, the I<sup>2</sup>C-bus master issues a STOP condition (P).

#### 7.8 Command decoder

The command decoder identifies command bytes that arrive on the I<sup>2</sup>C-bus. All available commands carry a continuation bit C in their most-significant bit position (see Fig.16). When this bit is set, it indicates that the next byte of the transfer to arrive will also represent a command.

If the bit is reset, it indicates the last command byte of the transfer. Further bytes will be regarded as display data.

The five commands available to the PCF8566 are defined in Table 5.



### Table 5 Definition of PCF8566 commands

		СОМ	MAN	D/OPC	ODE			OPTIONS	DESCRIPTION
Mod	e set						1		
С	1	0	LP	E	В	M1	M0	see Table 6	defines LCD drive mode
								see Table 7	defines LCD bias configuration
								see Table 8	defines display status; the possibility to disable the display allows implementation of blinking under external control
								see Table 9	defines power dissipation mode
Load	l data	point	er	•	•	•			
С	0	0	P4	P3	P2	P1	P0	see Table 10	five bits of immediate data, bits P4 to P0, are transferred to the data pointer to define one of twenty-four display RAM addresses
Devi	ce sel	lect							
С	1	1	0	0	A2	A1	A0	see Table 11	three bits of immediate data, bits A0 to A2, are transferred to the subaddress counter to define one of eight hardware subaddresses
Banl	sele	ct							
С	1	1	1	1	0	I	0	see Table 12	defines input bank selection (storage of arriving display data)
								see Table 13	defines output bank selection (retrieval of LCD display data)
									the BANK SELECT command has no effect in 1 : 3 and 1 : 4 multiplex drive modes
Blinl	<b>(</b>			•	•	•			
С	1	1	1	0	Α	BF1	BF0	see Table 14	defines the blinking frequency
								see Table 15	selects the blinking mode; normal operation with frequency set by bits BF1 and BF0, or blinking by alternation of display RAM banks. Alternation blinking does not apply in 1 : 3 and 1 : 4 multiplex drive modes

#### Table 6 LCD drive mode

LCD DRIVE MODE	BIT M1	BIT MO
Static (1 BP)	0	1
1 : 2 MUX (2 BP)	1	0
1 : 3 MUX (3 BP)	1	1
1 : 4 MUX (4 BP)	0	0

LCD BIAS	BIT B
<sup>1</sup> / <sub>3</sub> bias	0
<sup>1</sup> / <sub>2</sub> bias	1

Table 8Display status

DISPLAY STATUS	BIT E
Disabled (blank)	0
Enabled	1

Table 9 Power dissipation mode

MODE	BIT LP
Normal mode	0
Power-saving mode	1

#### Table 10 Load data pointer

BITS	P4	P3	P2	P1	P0	
5-bit binary value of 0 to 23						

Table 11 Device select

BITS	A0	A1	A2	
3-bit binary value of 0 to 7				

 Table 12
 Input bank selection

STATIC	1 : 2 MUX	BIT 1
RAM bit 0	RAM bits 0, 1	0
RAM bit 2	RAM bits 2, 3	1

 Table 13
 Output bank selection

STATIC	1 : 2 MUX	BIT 0
RAM bit 0	RAM bits 0, 1	0
RAM bit 2	RAM bits 2, 3	1

Table 14 Blinking frequency

BLINK FREQUENCY	BIT BF1	BIT BF0
Off	0	0
2 Hz	0	1
1 Hz	1	0
0.5 Hz	1	1

#### Table 15 Blink mode selection

BLINK MODE	BIT A
Normal blinking	0
Alternation blinking	1

#### 7.9 Display controller

The display controller executes the commands identified by the command decoder. It contains the status registers of the PCF8566 and coordinates their effects.

The controller is also responsible for loading display data into the display RAM as required by the filling order.

#### 7.10 Cascaded operation

In large display configurations, up to 16 PCF8566s can be distinguished on the same I<sup>2</sup>C-bus by using the 3-bit hardware subaddress (A0, A1 and A2) and the programmable I<sup>2</sup>C-bus slave address (SA0). It is also possible to cascade up to 16 PCF8566s. When cascaded, several PCF8566s are synchronized so that they can share the backplane signals from one of the devices in the cascade. Such an arrangement is cost-effective in large LCD applications since the outputs of only one device need to be through-plated to the backplane electrodes of the display. The other PCF8566s of the cascade contribute additional segment outputs but their backplane outputs are left open-circuit (Fig.17).

The <u>SYNC</u> line is provided to maintain the correct synchronization between all cascaded PCF8566s. This synchronization is guaranteed after the power-on reset. The only time that SYNC is likely to be needed is if synchronization is accidentally lost (e.g. by noise in adverse electrical environments; or by the definition of a multiplex mode when PCF8566s with differing SA0 levels are cascaded). SYNC is organized as an input/output pin; the output section being realized as an open-drain driver with an internal pull-up resistor. A PCF8566 asserts the SYNC line at the onset of its last active backplane signal and monitors the  $\overline{SYNC}$  line at all other times. Should synchronization in the cascade be lost, it will be restored by the first PCF8566 to assert SYNC. The timing relationships between the backplane waveforms and the SYNC signal for the various drive modes of the PCF8576 are shown in Fig.18. The waveforms are identical with the parent device PCF8576. Cascade ability between PCF8566s and PCF8576s is possible, giving cost effective LCD applications.



# Universal LCD driver for low multiplex rates



For single plane wiring of PCF8566s, see Chapter "Application information".

### 8 LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>DD</sub>	supply voltage	-0.5	+7	V
V <sub>LCD</sub>	LCD supply voltage	$V_{DD} - 7$	V <sub>DD</sub>	V
VI	input voltage (SCL, SDA, A0 to A2, OSC, CLK, SYNC and SA0)	$V_{SS} - 0.5$	V <sub>DD</sub> + 0.5	V
Vo	output voltage (S0 to S23 and BP0 to BP3)	$V_{LCD} - 0.5$	V <sub>DD</sub> + 0.5	V
I	DC input current	_	±20	mA
I <sub>O</sub>	DC output current	_	±25	mA
I <sub>DD</sub> , I <sub>SS</sub> , I <sub>LCD</sub>	$V_{DD}$ , $V_{SS}$ or $V_{LCD}$ current	-	±50	mA
P <sub>tot</sub>	power dissipation per package	_	400	mW
Po	power dissipation per output	_	100	mW
T <sub>stg</sub>	storage temperature	-65	+150	°C

#### 9 HANDLING

Inputs and outputs are protected against electrostatic discharges in normal handling. However, to be totally safe, it is advised to take handling precautions appropriate to handling MOS devices (see "Handling MOS devices").

### PCF8566

#### 10 DC CHARACTERISTICS

 $V_{SS}$  = 0 V;  $V_{DD}$  = 2.5 to 6 V;  $V_{LCD}$  =  $V_{DD}$  – 2.5 to  $V_{DD}$  – 6 V;  $T_{amb}$  = –40 to +85 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies		1	1	1	-	1
V <sub>DD</sub>	operating supply voltage		2.5	_	6	V
V <sub>LCD</sub>	LCD supply voltage		V <sub>DD</sub> – 6	_	V <sub>DD</sub> – 2.5	V
I <sub>DD</sub>	operating supply current (normal mode)	f <sub>CLK</sub> = 200 kHz; note 1	-	30	90	μA
I <sub>LP</sub>	power saving mode supply current	$\label{eq:V_DD} \begin{array}{l} V_{DD} = 3.5 \text{ V}; \ V_{LCD} = 0 \text{ V}; \\ f_{CLK} = 35 \text{ kHz}; \text{ A0}, \\ \text{A1 and A2 tied to } V_{SS}; \\ \text{note 1} \end{array}$	-	15	40	μΑ
Logic			•			
V <sub>IL</sub>	LOW level input voltage		V <sub>SS</sub>	_	0.3V <sub>DD</sub>	V
V <sub>IH</sub>	HIGH level input voltage		0.7V <sub>DD</sub>	_	V <sub>DD</sub>	V
V <sub>OL</sub>	LOW level output voltage	I <sub>O</sub> = 0 mA	-	_	0.05	V
V <sub>OH</sub>	HIGH level output voltage	I <sub>O</sub> = 0 mA	V <sub>DD</sub> - 0.05	_	-	V
I <sub>OL1</sub>	LOW level output current (CLK and SYNC)	V <sub>OL</sub> = 1 V; V <sub>DD</sub> = 5 V	1	_	-	mA
I <sub>OH</sub>	HIGH level output current (CLK)	V <sub>OH</sub> = 4 V; V <sub>DD</sub> = 5 V	-	_	-1	mA
I <sub>OL2</sub>	LOW level output current (SDA and SCL)	V <sub>OL</sub> = 0.4 V; V <sub>DD</sub> = 5 V	3	_	-	mA
ILI	leakage current (SA0, CLK, OSC, A0, A1, A2, SCL and SDA)	$V_{I} = V_{SS} \text{ or } V_{DD}$	-	-	±1	μΑ
I <sub>pd</sub>	pull-down current (A0, A1, A2 and OSC)	V <sub>I</sub> = 1 V; V <sub>DD</sub> = 5 V	15	50	150	μA
R <sub>puSYNC</sub>	pull-up resistor (SYNC)		15	25	60	kΩ
V <sub>ref</sub>	power-on reset level	note 2	_	1.3	2	V
t <sub>sw</sub>	tolerable spike width on bus		_	_	100	ns
Ci	input capacitance	note 3	-	_	7	pF
LCD outpu	uts	•	•			
$V_{BP}$	DC voltage component (BP0 to BP3)	C <sub>BP</sub> = 35 nF	_	±20	-	mV
Vs	DC voltage component (S0 to S23)	C <sub>S</sub> = 5 nF	-	±20	-	mV
Z <sub>BP</sub>	output impedance (BP0 to BP3)	$V_{LCD} = V_{DD} - 5$ V; note 4	-	1	5	kΩ
Z <sub>S</sub>	output impedance (S0 to S23)	$V_{LCD} = V_{DD} - 5$ V; note 4	-	3	7	kΩ

#### Notes

1. Outputs open; inputs at  $V_{SS}$  or  $V_{DD}$ ; external clock with 50% duty factor; I<sup>2</sup>C-bus inactive.

2. Resets all logic when  $V_{DD} < V_{ref}$ .

3. Periodically sampled, not 100% tested.

4. Outputs measured one at a time.

#### Product specification

### PCF8566

#### **11 AC CHARACTERISTICS**

 $V_{SS} = 0$  V;  $V_{DD} = 2.5$  to 6 V;  $V_{LCD} = V_{DD} - 2.5$  to  $V_{DD} - 6$  V;  $T_{amb} = -40$  to +85 °C; unless otherwise specified; note 1.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT	
f <sub>CLK</sub>	oscillator frequency (normal mode)	V <sub>DD</sub> = 5 V; note 2	125	200	315	kHz	
f <sub>CLKLP</sub>	oscillator frequency (power saving mode)	V <sub>DD</sub> = 3.5 V	21	31	48	kHz	
t <sub>CLKH</sub>	CLK HIGH time		1	_	-	μs	
t <sub>CLKL</sub>	CLK LOW time		1	_	-	μs	
t <sub>PSYNC</sub>	SYNC propagation delay		-	-	400	ns	
t <sub>SYNCL</sub>	SYNC LOW time		1	-	-	μs	
t <sub>PLCD</sub>	driver delays with test loads	$V_{LCD} = V_{DD} - 5 V$	-	-	30	μs	
l <sup>2</sup> C-bus						·	
t <sub>BUF</sub>	bus free time		4.7	_	-	μs	
t <sub>HD; STA</sub>	START condition hold time		4	_	-	μs	
t <sub>LOW</sub>	SCL LOW time		4.7	-	-	μs	
t <sub>HIGH</sub>	SCL HIGH time		4	_	-	μs	
t <sub>SU; STA</sub>	START condition set-up time (repeated start code only)		4.7	-	-	μs	
t <sub>HD; DAT</sub>	data hold time		0	_	-	μs	
t <sub>SU; DAT</sub>	data set-up time		250	-	-	ns	
t <sub>r</sub>	rise time		-	_	1	μs	
t <sub>f</sub>	fall time		-	-	300	ns	
t <sub>SU; STO</sub>	STOP condition set-up time		4.7	_	_	μs	

#### Notes

- 1. All timing values referred to  $V_{IH}$  and  $V_{IL}$  levels with an input voltage swing of  $V_{SS}$  to  $V_{DD}$ .
- 2. At  $f_{CLK}$  < 125 kHz, I<sup>2</sup>C-bus maximum transmission speed is derated.













#### 13 CHIP DIMENSIONS AND BONDING PAD LOCATIONS



### PCF8566

 Table 16 Bonding pad locations (dimensions in mm)

All x/y coordinates are referenced to centre of chip, (see Fig.25).

PAD NUMBER	SYMBOL	x	У	PIN
1	SDA	200	-1235	1
2	SCL	400	-1235	2
3	SYNC	605	-1235	3
4	CLK	856	-1235	4
5	V <sub>DD</sub>	1062	-1235	5
6	OSC	1080	-1025	6
7	A0	1080	-825	7
8	A1	1080	-625	8
9	A2	1080	-425	9
10	SA0	1080	-225	10
11	V <sub>SS</sub>	1080	-25	11
12	V <sub>LCD</sub>	1080	347	12
13	BP0	1080	547	13
14	BP2	1080	747	14
15	BP1	1080	947	15
16	BP3	1074	1235	16
17	S0	674	1235	17
18	S1	674	1235	18
19	S2	474	1235	19
20	S3	274	1235	20
21	S4	-274	1235	21
22	S5	-474	1235	22
23	S6	-674	1235	23
24	S7	-874	1235	24
25	S8	-1074	1235	25
26	S9	-1080	765	26
27	S10	-1080	565	27
28	S11	-1080	365	28
29	S12	-1080	165	29
30	S13	-1080	-35	30
31 S14		-1080	-235	31
32	S15	-1080	-435	32
33	S16	-1080	-635	33
34	S17	-1080	-835	34
35	S18	-1080	-1035	35
36	S19	-1056	-1235	36
37	S20	-830	-1235	37
38	S21	-630	-1235	38
39	S22	-430	-1235	39
40	S23	-230	-1235	40

1997 Apr 02

ŧ

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	с	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	м <sub>н</sub>	w	Z <sup>(1)</sup> max.
mm	4.7	0.51	4.0	1.70 1.14	0.53 0.38	0.36 0.23	52.50 51.50	14.1 13.7	2.54	15.24	3.60 3.05	15.80 15.24	17.42 15.90	0.254	2.25
inches	0.19	0.020	0.16	0.067 0.045	0.021 0.015	0.014 0.009	2.067 2.028	0.56 0.54	0.10	0.60	0.14 0.12	0.62 0.60	0.69 0.63	0.01	0.089

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT129-1	051G08	MO-015AJ				<del>-92-11-17</del> 95-01-14	

PCF8566

ME

A



### rates

seating plane

L

#### 14 PACKAGE OUTLINES

### DIP40: plastic dual in-line package; 40 leads (600 mil)

D

Universal LCD driver for low multiplex

#### **Philips Semiconductors**

SOT129-1

rates

PCF8566

# Universal LCD driver for low multiplex



SOT158-1

 $\square$ 

95-01-24

### PCF8566

#### 15 SOLDERING

#### 15.1 Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

#### 15.2 DIP

15.2.1 SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ( $T_{stg\,max}$ ). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

#### 15.2.2 REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than  $300 \,^{\circ}$ C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400  $^{\circ}$ C, contact may be up to 5 seconds.

#### 15.3 SO and VSO

#### 15.3.1 REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO and VSO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement. Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45  $^{\circ}$ C.

#### 15.3.2 WAVE SOLDERING

Wave soldering techniques can be used for all SO and VSO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

#### 15.3.3 REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

#### **16 DEFINITIONS**

Data sheet status						
Objective specification	This data sheet contains target or goal specifications for product development.					
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.					
Product specification	This data sheet contains final product specifications.					
Limiting values						
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.						
Application information						

Where application information is given, it is advisory and does not form part of the specification.

#### 17 LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

#### 18 PURCHASE OF PHILIPS I<sup>2</sup>C COMPONENTS



Purchase of Philips I<sup>2</sup>C components conveys a license under the Philips' I<sup>2</sup>C patent to use the components in the I<sup>2</sup>C system provided the system conforms to the I<sup>2</sup>C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

PCF8566

NOTES

PCF8566

NOTES

PCF8566

NOTES

### Philips Semiconductors – a worldwide company

Argentina: see South America Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113, Tel. +61 2 9805 4455, Fax. +61 2 9805 4466 Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213, Tel. +43 1 60 101. Fax. +43 1 60 101 1210 Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6, 220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773 Belgium: see The Netherlands Brazil: see South America Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor, 51 James Bourchier Blvd., 1407 SOFIA, Tel. +359 2 689 211, Fax. +359 2 689 102 Canada: PHILIPS SEMICONDUCTORS/COMPONENTS, Tel. +1 800 234 7381 China/Hong Kong: 501 Hong Kong Industrial Technology Centre, 72 Tat Chee Avenue, Kowloon Tong, HONG KONG, Tel. +852 2319 7888, Fax. +852 2319 7700 Colombia: see South America Czech Republic: see Austria Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S, Tel. +45 32 88 2636, Fax. +45 31 57 1949 Finland: Sinikalliontie 3, FIN-02630 ESPOO, Tel. +358 9 615800, Fax. +358 9 61580/xxx France: 4 Rue du Port-aux-Vins. BP317. 92156 SURESNES Cedex. Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427 Germany: Hammerbrookstraße 69, D-20097 HAMBURG, Tel. +49 40 23 53 60, Fax. +49 40 23 536 300 Greece: No. 15, 25th March Street, GR 17778 TAVROS/ATHENS, Tel. +30 1 4894 339/239, Fax. +30 1 4814 240 Hungary: see Austria India: Philips INDIA Ltd, Shivsagar Estate, A Block, Dr. Annie Besant Rd. Worli, MUMBAI 400 018, Tel. +91 22 4938 541, Fax. +91 22 4938 722 Indonesia: see Singapore Ireland: Newstead, Clonskeagh, DUBLIN 14, Tel. +353 1 7640 000. Fax. +353 1 7640 200 Israel: RAPAC Electronics, 7 Kehilat Saloniki St, TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007 Italy: PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3, 20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557 Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108, Tel. +81 3 3740 5130, Fax. +81 3 3740 5077 Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL, Tel. +82 2 709 1412, Fax. +82 2 709 1415 Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR, Tel. +60 3 750 5214, Fax. +60 3 757 4880 Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905, Tel. +9-5 800 234 7381 Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB, Tel. +31 40 27 82785, Fax. +31 40 27 88399 New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND, Tel. +64 9 849 4160, Fax. +64 9 849 7811 Norway: Box 1, Manglerud 0612, OSLO, Tel. +47 22 74 8000, Fax. +47 22 74 8341 Philippines: Philips Semiconductors Philippines Inc., 106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI, Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474 Poland: UI. Lukiska 10, PL 04-123 WARSZAWA, Tel. +48 22 612 2831, Fax. +48 22 612 2327 Portugal: see Spain Romania: see Italy Russia: Philips Russia, UI. Usatcheva 35A, 119048 MOSCOW, Tel. +7 095 755 6918, Fax. +7 095 755 6919 Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231, Tel. +65 350 2538, Fax. +65 251 6500 Slovakia: see Austria Slovenia: see Italy South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale, 2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000, Tel. +27 11 470 5911, Fax. +27 11 470 5494 South America: Rua do Rocio 220, 5th floor, Suite 51, 04552-903 São Paulo, SÃO PAULO - SP, Brazil, Tel. +55 11 821 2333, Fax. +55 11 829 1849 Spain: Balmes 22 08007 BARCELONA Tel. +34 3 301 6312. Fax. +34 3 301 4107 Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM, Tel. +46 8 632 2000, Fax. +46 8 632 2745 Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH, Tel. +41 1 488 2686, Fax. +41 1 481 7730 Taiwan: Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1, TAIPEI, Taiwan Tel. +886 2 2134 2870, Fax. +886 2 2134 2874 Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd. 209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260, Tel. +66 2 745 4090, Fax. +66 2 398 0793 Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL, Tel. +90 212 279 2770, Fax. +90 212 282 6707 Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7, 252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461 United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Haves. MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409, Tel. +1 800 234 7381

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD, Tel. +381 11 625 344, Fax.+381 11 635 777

For all other countries apply to: Philips Semiconductors, Marketing & Sales Communications, Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

© Philips Electronics N.V. 1997

SCA53

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

417067/1200/05/pp40

Date of release: 1997 Apr 02

Document order number: 9397 750 01755

Let's make things better.

Internet: http://www.semiconductors.philips.com



